TIMTRONICS
THERMAL INTERFACE MATERIALS

DATA SHEET

TIM-PC 8550TC

Thermally Conductive Silicone Potting Compound

DESCRIPTIONS

TIM-PC 8550TC is a two parts, thermally conductive, low viscosity thixotropic compounds which cures at room temperature or can be accelerated with heat. Specially designed to achieve low hardness and primer-less adhesion to substrates includes metals, plastics and ceramics. Excellent dielectric encapsulation and vibration absorption.

Applications: Potting and encapsulating of Equipment modules, Power supplies, relays and amplifiers, Transformers, coils and ferrite cores. Fiber optic wave guide coatings. Encapsulation of circuit boards

INSTRUCTION FOR USE

1. Thoroughly stir both parts prior to mixing together.
2. **Mixing by Hand:** Combine equal part of A & B components by weight, mix until completely mixed. Use care when mixing to minimize air entrapment. Avoid foreign contaminations.
3. **Mixing and dispensing with automated equipment**: Use properly ratio equipment (1:1), use mixing system that will properly mix part A & B. Mixed parts will have short pot life, refer data sheet.

Note: Refer to Safety Data Sheet **(SDS)** for additional health and safety information.

AVAILABILITY

2 Parts Kits: 1 Quart, 1 gallon & 5 gallon pail.

Property	Results
Special Future	Flame Retardant. Self-Bonding Flexible, impact and thermal shock resistance.
Type	Two Parts
Mix Ratio by Weight (A/H)	1:1
Shelf Life	12 months@ 25°C
Mixed Viscosity @25°C cp	4000
Gel Time (Pot Life) (100 grams)	1 hr @ 25°C
Cure Schedule	24-48 hrs@ 25°C or 2 hrs @ 70°C
Cured Properties	
Color	Gray
Specific Gravity	2.15
Hardness (Shore)	A-42
Tensile Strength	>250psi
Elongation	40%
Service Temperature Range	-55°C to 200°C
THERMAL	
Thermal Conductivity (W/m-K)	**1.2**
ELECTRICAL	
Dielectric Strength (KV/mm)	17.5
Dielectric Constant	5.0
Volume Resistivity (Ohm-cm)	10^14